

Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 26 D-32758 Detmold Germany

www.weidmueller.com

Product image



















High-temperature resistant, double level, laterally offset, male connector with flange or solder flange. 1.5 mm solder pin is suitable for reflow soldering. 3.2 mm solder pin suitable for reflow and wave soldering. The pin headers provide space for labelling and can be coded.

General ordering data

Version	PCB plug-in connector, male header, Flange / Solder flange, THT/THR solder connection, 5.08 mm, Number of poles: 32, 180°, Solder pin length (I): 4.5 mm, tinned, black, Box
Order No.	<u>1934150000</u>
Туре	SLDV-THR 5.08/32 FLF4.5SN SW
GTIN (EAN)	4032248589500
Qty.	12 pc(s).
Product data	IEC: 400 V / 15 A
	UL: 300 V / 10 A
Packaging	Вох

Creation date June 9, 2024 1:27:11 AM CEST



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Technical data

Dimensions and weights

Depth	23.67 mm	Depth (inches)	0.932 inch
Height	30.66 mm	Height (inches)	1.207 inch
Height of lowest version	26.16 mm	Width	91.44 mm
Width (inches)	3.6 inch	Net weight	26.4 g

System specifications

Product family	OMNIMATE Signal - series	Type of connection	
	BL/SL 5.08		Board connection
Mounting onto the PCB	THT/THR solder connec-	Pitch in mm (P)	
	tion		5.08 mm
Pitch in inches (P)	0.2 "	Outgoing elbow	180°
Number of poles	32	Number of solder pins per pole	1
Solder pin length (I)	4.5 mm	Solder pin length tolerance	0 / -0.3 mm
Solder pin dimensions	d = 1.2 mm, Octagonal	Solder eyelet hole diameter (D)	1.5 mm
Solder eyelet hole diameter tolerance (I	D)+ 0,1 mm	L1 in mm	76.2 mm
L1 in inches	3 "	Pin series quantity	2
Touch-safe protection acc. to DIN VDE	finger-safe unplugged/	Touch-safe protection acc. to DIN VDE	IP20 plugged/ IP10 un-
57 106	back-of-hand-safe plugged	0470	plugged
Protection degree	IP20	Volume resistance	≤5 mΩ
Can be coded	Yes	Plugging force/pole, max.	10 N
Pulling force/pole, max.	7.5 N		

Material data

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	Illa
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	Cu-alloy
Contact surface		Layer structure of solder connection	13 μm Ni / 24 μm Sn
	tinned		matt
Layer structure of plug contact	13 μm Ni / 24 μm Sn	Storage temperature, min.	
	matt		-40 °C
Storage temperature, max.	70 °C	Operating temperature, max.	100 °C
Temperature range, installation, max.	100 °C		

Rated data acc. to IEC

tested acc. to standard		Rated current, min. number of poles	
	IEC 60664-1, IEC 61984	(Tu=20°C)	15 A
Rated current, max. number of poles (Tu=20°C)	10.5 A	Rated current, min. number of poles (Tu=40°C)	13 A
Rated current, max. number of poles (Tu=40°C)	9 A	Rated voltage for surge voltage class / pollution degree II/2	400 V
Rated voltage for surge voltage class / pollution degree III/2	320 V	Rated voltage for surge voltage class / pollution degree III/3	250 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	4 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	4 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	4 kV	Short-time withstand current resistance	1 x 1s with 120 A



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Institute (CSA)	€	Certificate No. (CSA)	
			200039-1121690
Rated voltage (Use group B / CSA)	300 V	Rated voltage (Use group D / CSA)	300 V
Rated current (Use group B / CSA)	10 A	Rated current (Use group D / CSA)	10 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.		
Rated data acc. to UL 1059			
Rated voltage (Use group B / UL 1059)	200 V	Rated voltage (Use group D / UL 1059)	200 V
Rated current (Use group B / UL 1059)		Rated current (Use group D / UL 1059)	
nated current (Ose group B / OL 1059)	IU A	hated current (Ose group D / OL 1059)	10 A
Packing			
Packaging	Box	VPE length	347 mm
VPE width	139 mm	VPE height	45 mm
Classifications			
ETIM 6.0	EC002637	ETIM 7.0	EC002637
ETIM 8.0	EC002637	ETIM 9.0	EC002637
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01
ECLASS 12.0	27-46-02-01	ECLASS 13.0	27-46-02-01
Important note			
IPC conformity	Conformity The products are d	evalened manufactured and delivered	international reas == :==
ire comornity	Conformity: The products are developed, manufactured and delivered according international recognized stards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties.		

dards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.

· Rated current related to rated cross-section & min. No. of poles.

- Spacing between rows: see hole layout
- P on drawing = pitch
- Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards.
- · In accordance with IEC 61984, OMNIMATE-connectors are connectors without breaking capacity (COC). During designated use, connectors are not allowed to be engaged or disengaged when live or under load
- Long term storage of the product with average temperature of 50 °C and maximum humidity 70%, 36 months

Approvals

Notes

Approvals



ROHS Conform

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Downloads

Product Change Notification	Anpassung Verpackung SLDV-THR_5.08
	Change of packaging_SLDV-THR 5.08
Catalogues	Catalogues in PDF-format
Brochures	FL DRIVES EN
	<u>FL DRIVES DE</u>
White paper surface mount technology	Download Whitepaper



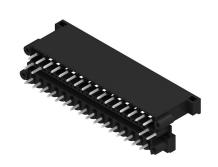
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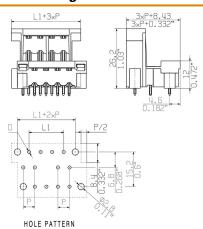
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Drawings

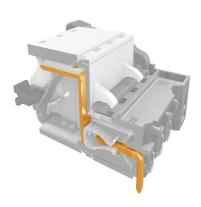
Product image



Dimensional drawing



Product benefits



Safe power transmission Proven properties



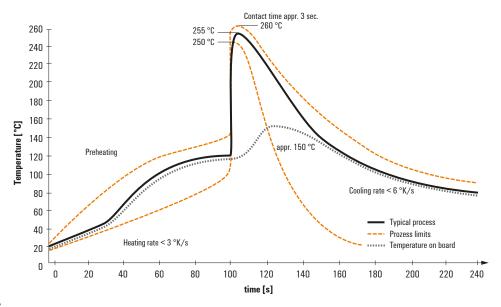
Recommended wave solderding profiles

Weidmüller Interface GmbH & Co. KG

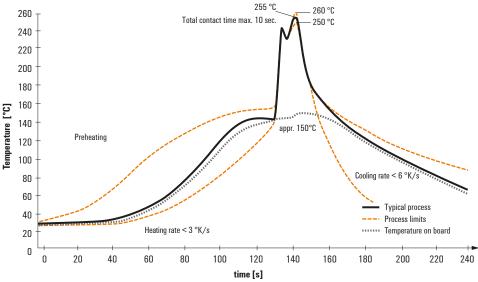
Klingenbergstraße 16 D-32758 Detmold Germany

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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

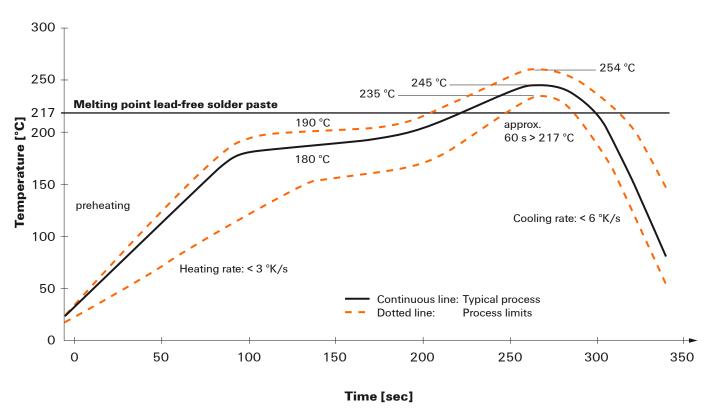


Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- · Time for pre heating
- Maximum temperature
- Time above melting point
- · Time for cooling
- · Maximum heating rate
- · Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3$ K/s. In parallel the solder paste is ,activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at \geq -6K/s solder is cured. Board and components cool down while avoiding cold cracks.